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December 2013

### FQPF9N50CF

### N-Channel QFET® FRFET® MOSFET

500 V, 9 A, 850 mΩ

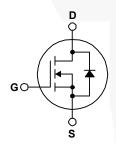
### **Description**

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and • Fast Recovery Body Diode (Typ. 100 ns) electronic lamp ballasts.

#### **Features**

- 9 A, 500 V,  $R_{DS(on)}$  = 850 m $\Omega$  (Max.) @  $V_{GS}$  = 10 V,  $I_D$  = 4.5 A
- Low Gate Charge (Typ. 28 nC)
- Low Crss (Typ. 24 pF)
- 100% Avalanche Tested





### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQPF9N50CF	Unit
$V_{DSS}$	Drain-Source Voltage		500	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		9*	Α
	- Continuous (T <sub>C</sub> = 100°C)		5.4*	Α
$I_{DM}$	Drain Current - Pulsed	(Note 1)	36*	Α
$V_{GSS}$	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	360	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	9	Α
$E_AR$	Repetitive Avalanche Energy	(Note 1)	4.4	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C)		44	W
	- Derate above 25°C		0.35	W/°C
$T_J,T_STG$	Operating and Storage Temperature Range		-55 to +150	°C
$T_L$	Maximum Lead Temperature for Soldering,			

### **Thermal Characteristics**

Symbol	Parameter	FQPF9N50CF	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	2.86	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	*C/VV

### **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQPF9N50CF	FQPF9N50CF	TO-220F	Tube	N/A	N/A	50 units

### **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_D = 250  \mu\text{A}$	500			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.57		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	rain Current V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V			10	μА
		V <sub>DS</sub> = 400 V, T <sub>C</sub> = 125°C			100	μА
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V		-	-100	nA
On Charact	teristics					1
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.5 A		0.70	0.85	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 4.5 A		6.5		S
Dynamic C	haracteristics					1
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,		790	1030	р₹
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		130	170	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		\	24	30	pF
Switching C	Characteristics				1	
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 250 V, I <sub>D</sub> = 9A,		18	45	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$		65	140	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			93	195	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	/	64	125	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 9A,	/	28	35	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V	-	4		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4)	/	15		nC
Drain-Sour	ce Diode Characteristics and Maximum Ratings	3				1
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				9*	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				36*	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 9 A			1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 9 A,		100		ns
Q <sub>rr</sub>	Reverse Recovery Charge	dl <sub>F</sub> / dt = 100 A/μs		0.3	//	μС

#### NOTES:

<sup>1.</sup> Repetitive rating : pulse-width limited by maximum junction temperature.

<sup>2.</sup> L = 8 mH,  $I_{AS}$  = 9 A,  $V_{DD}$  = 50 V,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C.

 $<sup>3.~</sup>I_{SD} \leq 11~A,~di/dt \leq 200~A/\mu s,~V_{DD} \leq BV_{DSS,}~Starting~~T_J = 25^{\circ}C.$ 

<sup>4.</sup> Essentially independent of operating temperature.

### **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

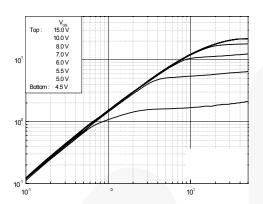


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

Figure 2. Transfer Characteristics

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

**Figure 5. Capacitance Characteristics** 

Figure 6. Gate Charge Characteristics

### **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

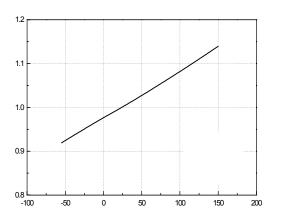


Figure 8. On-Resistance Variation vs. Temperature

Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

V<sub>DS</sub>, Drain-Source Voltage [V]

**Figure 11. Transient Thermal Response Curve** 

Z<sub>eJC</sub>(t), Thermal Response [°C/W]

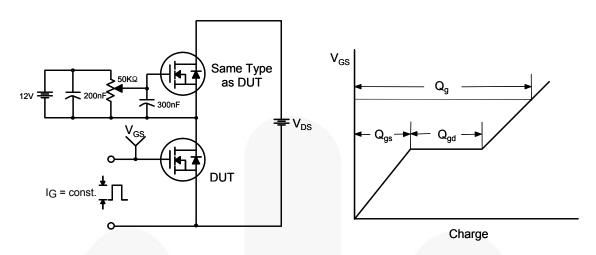


Figure 12. Gate Charge Test Circuit & Waveform

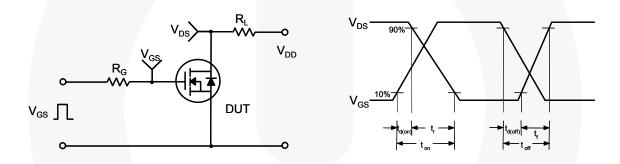


Figure 13. Resistive Switching Test Circuit & Waveforms

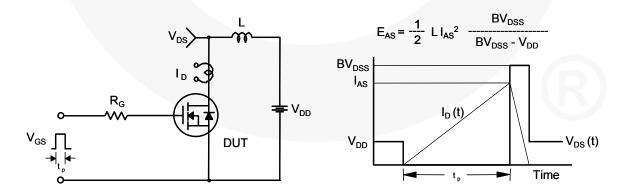


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

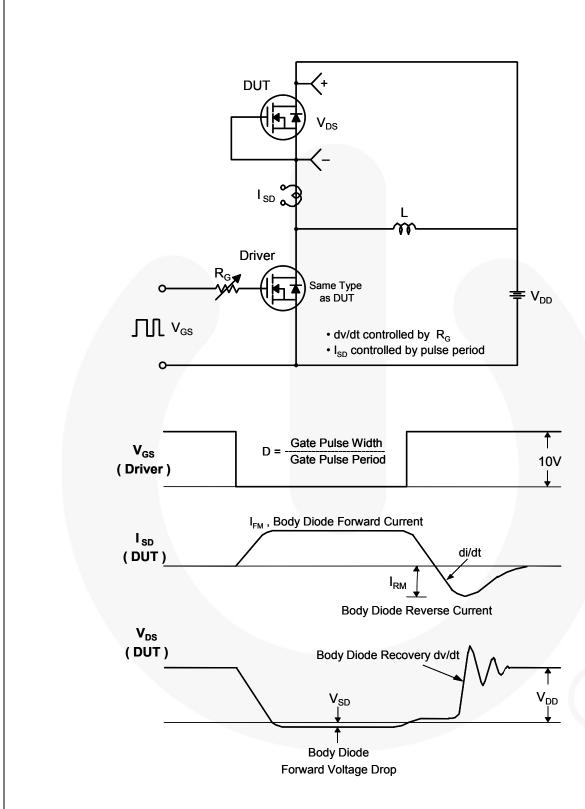


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

### **Mechanical Dimensions**

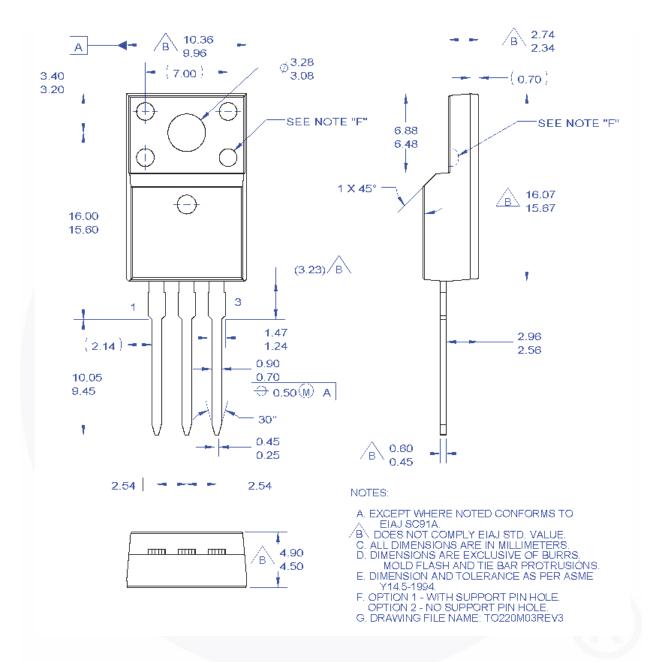


Figure 16. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead

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